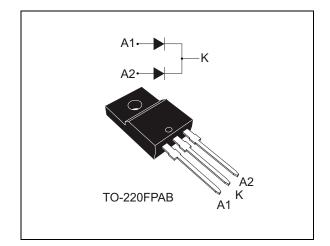


# FERD40U50C

### Field effect rectifier

#### **Datasheet - production data**



### Features

- ST advanced rectifier process
- Stable leakage current over reverse voltage
- Reduced leakage current
- Low forward voltage drop
- High frequency operation
- Insulated package: TO-220FPAB
  - Insulating voltage: 2000 V<sub>RMS</sub> sine

### Description

This dual rectifier is based on a proprietary technology that achieved the best in class  $V_{\rm F}/I_{\rm R}$  for a given silicon surface.

Packaged in TO-220FPAB, this device is intended to be used in rectification and freewheeling operations in switch-mode power supplies.

Table	1.	Device	summary
TUDIC		Device	Summary

Symbol	Value
I <sub>F(AV)</sub>	2 x 20 A
V <sub>RRM</sub>	50 V
T <sub>j</sub> (max)	+175 °C
V <sub>F</sub> (typ)	0.43 V

This is information on a product in full production.

# 1 Characteristics

#### Table 2. Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Parameter			Value	Unit
Repetitive peak reverse voltage			50	V
Forward rms current			40	А
Average forward current $\delta = 0.5$	T <sub>c</sub> = 120 °C	Per diode	20	А
Average forward current, 0 = 0.5	T <sub>c</sub> = 90 °C	Per device	40	~
Surge non repetitive forward current t <sub>p</sub> = 10 ms sinusoidal			250	А
Storage temperature range -65 to -			-65 to + 175	°C
Maximum operating junction temperature			175	°C
-	Repetitive peak reverse voltage Forward rms current Average forward current, $\delta = 0.5$ Surge non repetitive forward current Storage temperature range	Repetitive peak reverse voltageForward rms currentForward rms current $T_c = 120 \text{ °C}$ Average forward current, $\delta = 0.5$ $T_c = 90 \text{ °C}$ Surge non repetitive forward current $t_p = 10 \text{ ms sin}$ Storage temperature range $T_c = 10 \text{ ms sin}$	Repetitive peak reverse voltageForward rms currentAverage forward current, $\delta = 0.5$ $T_c = 120 \ ^{\circ}C$ Per diode $T_c = 90 \ ^{\circ}C$ Per deviceSurge non repetitive forward current $t_p = 10 \ ^{\circ}ms \$	Repetitive peak reverse voltage50Forward rms current40Average forward current, $\delta = 0.5$ $T_c = 120 \ ^{\circ}C$ Per diode20 $T_c = 90 \ ^{\circ}C$ Per device40Surge non repetitive forward current $t_p = 10 \ ^{\circ}ms \ ^{\circ}sinus \ $

1.  $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink.

#### Table 3. Thermal resistance

Symbol	Parameter	Value (max)	Unit	
D	Junction to case	Per diode	4.1	
R <sub>th(j-c)</sub>		Total	3.3	°C/W
R <sub>th(c)</sub>	Coupling		2.4	

When diodes 1 and 2 are used simultaneously:

 $T_{j(diode1)} = P_{(diode1)} \times R_{th(j-c)}(per diode) + P_{(diode2)} \times R_{th(c)}$ 

#### Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test co	nditions	Min.	Тур.	Max.	Unit
		T <sub>j</sub> = 25 °C	V - V			0.8	mA
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 125 °C	$V_R = V_{RRM}$		30	60	mA
IR Y	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = 35 V			460	μΑ
		T <sub>j</sub> = 125 °C			20	40	mA
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 5 A		0.25		
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 10 A		0.33		
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A		0.41	0.46	V
VF'	V <sub>F</sub> <sup>(-)</sup> Forward voltage drop	T <sub>j</sub> = 125 °C			0.39	0.43	v
		T <sub>j</sub> = 25 °C	L - 20 A		0.44	0.49	
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 20 A		0.43	0.48	

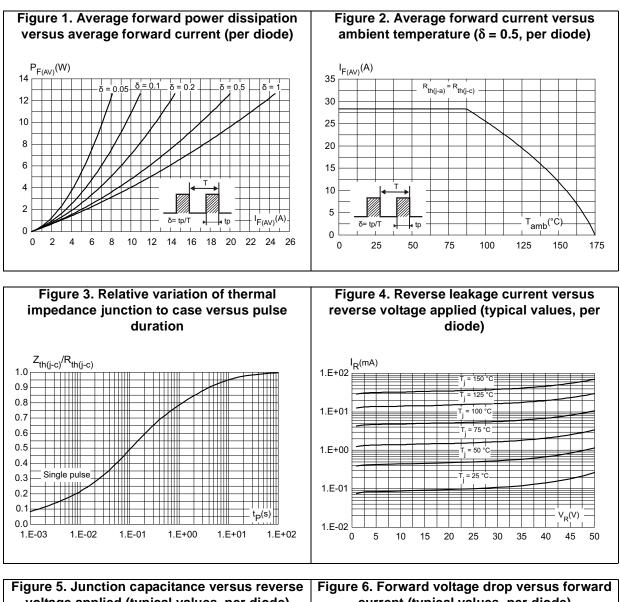
1. Pulse test:  $t_p = 5 \text{ ms}, \delta < 2\%$ 

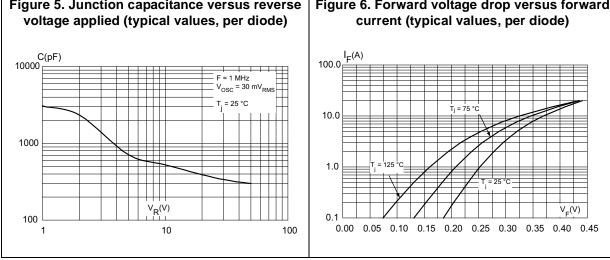
2. Pulse test:  $t_p$  = 380 µs,  $\delta$  < 2%

To evaluate the conduction losses use the following equation:

 $P = 0.329 \text{ x } I_{F(AV)} + 0.007 I_{F}^{2}_{(RMS)}$ 









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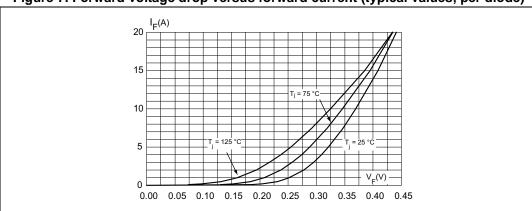


Figure 7. Forward voltage drop versus forward current (typical values, per diode)



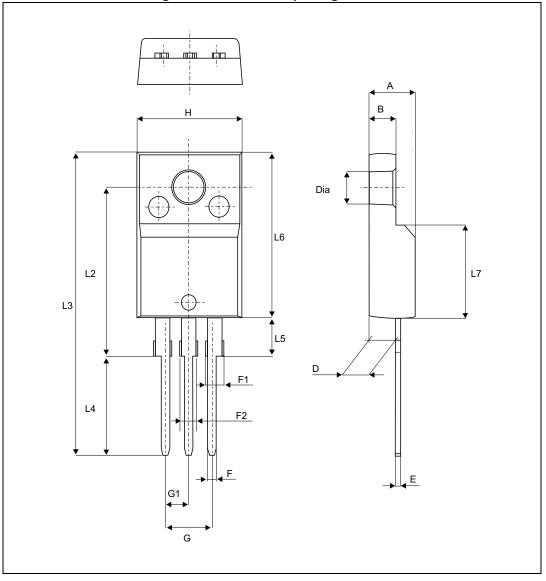
## 2 Package information

- Epoxy meets UL94, V0
- Recommended torque value for TO-220FPAB: 0.55 N.m
- Maximum torque value for TO-220FPAB: 0.7 N.m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.

### 2.1 TO-220FPAB package information

Figure 8. TO-220FPAB package outline





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			Dime	ensions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.70	0.018		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.70	0.045		0.067
F2	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16 Тур.			0.63 Тур.	
L3	28.6		30.6	1.126		1.205
L4	9.8		10.6	0.386		0.417
L5	2.9		3.6	0.114		0.142
L6	15.9		16.4	0.626		0.646
L7	9.00		9.30	0.354		0.366
Dia.	3.00		3.20	0.118		0.126

#### Table 5. T0-220FPAB package mechanical data

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# **3** Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
FERD40U50CFP	FERD40U50CFP	TO-220FPAB	1.9 g	50	Tube

# 4 Revision history

Table 7. Document revision history	Table 7.	Document	revision	history
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Date	Revision	Changes
17-Jun-2015	1	Initial release.



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